



# **RF430CL330H Device Erratasheet**

## 1 Silicon Revision D

See Section 4 for prior silicon revisions.

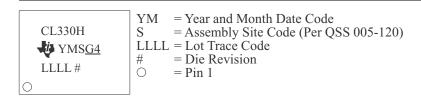
✓ The checkmark means that the issue is present in the specified revision.

Device	Rev:	DID	RF_Lock
RF430CL330H	D	1	>

## 2 Package Marking

**PW14** 

## TSSOP (PW), 14 Pin





Detailed Bug Description

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# 3 Detailed Bug Description

DID	DID – Bug description					
Description	RF430CL330H does not respond to PCD commands issued using a DID value other than 0x00.					
Workaround	PCD must issue commands with DID value of 0x00 or no DID present.					
RF_Lock	RF_Lock – Bug description					
Description	The RF430CL330H might become unresponsive in RF Enable Mode in a very small percentage of RF interactions between the RF430CL330H and the reader.					
Workaround	To ensure that this behavior does not happen in any case, an additional initialization sequence needs to be added. The following code snippet shows this initialization sequence.					
	This sequence has to be applied only once after every power-on and reset.					
	/**************************************					
	<pre>/* Errata Fix : Unresponsive RF - recommended firmware */ // Write_Register (address_16_bit, data_16_bit); // data_16_bit Read_Register (address_16_bit); /************************************</pre>					
	<pre>{     //Please implement this fix as given in this block. It is important that     //no line be removed or changed.     unsigned int version;     version = Read_Register(VERSION_REG); // read the version register.</pre>					



## 4 Prior Silicon Revisions

### 4.1 Silicon Revision C

✓ The checkmark means that the issue is present in the specified revision.

Device	Rev:	BIP-8	ATQB_1	ATQB_2	ATTRIB_1	ATTRIB_2		RF_Lock	RFU_BLK	ATQB_3	LAYER4_2
RF430CL330H	С	~	1	~	1	1	1	1	1	1	~



Prior Silicon Revisions

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## 4.2 Detailed Bug Description

BIP-8	BIP-8 - Bug description
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**Description** Addressing a device other than RF430CL330H on the same I2C bus results in incorrect data returned when BIP-8 is enabled on a multi-device I2C system.

Workaround BIP-8 must not be used on multi device I2C systems.

#### ATQB\_1 ATQB\_1 - Bug description

Description

NFC Forum specifies that tag must respond with '00' in bits 2 and 3 of the protocol\_type field, but RF430CL330H responds with '10'.

1 <sup>st</sup> byte	$2^{nd}$ , $3^{rd}$ , $4^{th}$ , $5^{th}$ bytes	6 <sup>th</sup> , 7 <sup>th</sup> , 8 <sup>th</sup> , 9 <sup>th</sup> bytes	10 <sup>th</sup> , 11 <sup>th</sup> , 12 <sup>th</sup> bytes	13 <sup>th</sup> , 14 <sup>th</sup> bytes
<b>'50'</b>	PUPI	Application Data	Protocol Info	CRC_B
(1 byte)	(4 bytes)	(4 bytes)	(3 bytes)	(2 bytes)

1 <sup>st</sup> byte	2 <sup>nd</sup> b	3 <sup>rd</sup> byte			4 <sup>th</sup> byte (optional) Extended ATQB		
Bit_Rate_capability	Max_Frame_Size	Protocol_Type	FWI	ADC	FO	SFGI	RFU
(8 bits)	(4 bits)	(4 bits)	(4 bits)	(2 bits)	(2 bits)	(4 bits)	(4 bits)

#### Figure 1. ATQB Response

Workaround The ATQB response is hard coded and cannot be changed. A fix is scheduled for silicon revision D.

#### ATQB\_2 ATQB\_2 - Bug description

Description

NFC Forum specifies that FWI (frame waiting time integer) must be between 0 and 8. RF430CL330H responds with FWI of 10, which is allowed per ISO 14443-3.

1 <sup>st</sup> byte	$2^{nd}$ , $3^{rd}$ , $4^{th}$ , $5^{th}$ bytes	$6^{th},7^{th},8^{th},9^{th}$ bytes	10 <sup>th</sup> , 11 <sup>th</sup> , 12 <sup>th</sup> bytes	13 <sup>th</sup> , 14 <sup>th</sup> bytes
<b>'50'</b>	PUPI	Application Data	Protocol Info	CRC_B
(1 byte)	(4 bytes)	(4 bytes)	(3 bytes)	(2 bytes)

1 <sup>st</sup> byte	2 <sup>nd</sup> byte		2 <sup>nd</sup> byte 3 <sup>rd</sup> byte			4 <sup>th</sup> byte (optional) Extended ATQB	
Bit_Rate_capability	Max_Frame_Size	Protocol_Type	FWI	ADC	FO	SFGI	RFU
(8 bits)	(4 bits)	(4 bits)	(4 bits)	(2 bits)	(2 bits)	(4 bits)	(4 bits)

Figure 2. ATQB Response

Workaround

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The ATQB response is hard coded and cannot be changed. A fix is scheduled for silicon revision D.

#### ATTRIB\_1 ATTRIB\_1 – Bug description

**Description** NFC Forum requires accepting a Higher Layer INF command with ATTRIB, but does not require supporting its functionality (must respond to only the base message). RF430CL330H does not respond to commands containing the Higher Layer INF field included.

1 <sup>st</sup> byte	$2^{nd}$ , $3^{rd}$ , $4^{th}$ , $5^{th}$ bytes	6 <sup>th</sup> byte	7 <sup>th</sup> byte	8 <sup>th</sup> byte	9 <sup>th</sup> byte	10 <sup>th</sup> bytes	
'1D'	Identifier	Param 1	Param 2	Param 3	Param 4	Higher layer INF	CRC_B
(1 byte)	(4 bytes)	(1 byte)	(1 byte)	(1 byte)	(1 byte)	(optional – 0 or more bytes)	(2 bytes)

#### Figure 3. ATTRIB Command

Workaround No workaround for revision C. A fix is scheduled for silicon revision D.

#### ATTRIB\_2 ATTRIB\_2 – Bug description

**Description** NFC Forum specifies that the answer to ATTRIB must be '0h'. RF430CL330H responds with '8h' to indicate the MBLI (maximum buffer length index).

15	byte	2 <sup>nd</sup> bytes	
MBLI	CID	Higher layer Response	CRC_B
(1	byte)	(optional 0 or more bytes)	(2 bytes)

Figure 4. Answer to ATTRIB

Workaround	The answer to ATTRIB is hard coded and cannot be changed. A fix is scheduled for silicon revision D.
INV_CMD	INV_CMD – Bug description
Description	RF430CL330H responds to invalid ATTRIB commands. NFC Forum specifies that the tag should not respond to invalid commands.
	Invalid ATTRIB Commands:
	1D + NFCID0 + '00 F8 01 00' (indicates 848kbps when 106kbps should be used)
	1D + NFCID0 + '00 08 00 00' (indicates PICC not compliant to 14443-4)
	1D + NFCID0 + '00 08 0F 00' (RFU bits must be set to '0' in PARAM3)
Workaround	No workaround available in revision C. A fix is scheduled for silicon revision D.



Prior Silicon Revisions

RFU_BLK	RFU_BLK – Bug description
Description	RF430CL330H does not respond to I-, R-, and S-Block commands with RFU bits set. NFC Forum specifies that the tag must ignore these bits and respond to the base message.
Workaround	No workaround available in revision C. A fix is scheduled for silicon revision D.
ATQB_3	ATQB_3 – Bug description
Description	REQB command with b5 set (Extended SENSB_RES supported) is responded with standard ATQB.
Workaround	No workaround available in revision C. A fix is scheduled for revision D.
LAYER4_2	LAYER4_2 – Bug description
Description	Upon receiving an unsupported C-APDU select command, RF430Cl330H responds with a PCB byte and it's PUPI. The response should be PCB byte and an error code.
Workaround	No workaround available in revision C. A fix is scheduled for revision D.



# **Document Revision History**

#### Changes from C Revision (September 2013) to D Revision

#### Page

•	Changed current silicon revision from C to D	1
•	Updated bug list applicable to silicon revision D	1
•	Added Section 2	1
•	Added DID description	2
•	Moved silicon revision C information and all bug descriptions that do not apply to silicon revision D to Section 4	3

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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